

EMI Shielding Materials

ASSEMBLY-LEVEL EMI SHIELDING COATINGS

Product Name	Description	Key Attributes	Attenuation	Sheet Resistance (Ω/sq/25 μm)	Surfaces	Coverage at 10 µm (m²/kg)	Recommended Cure
LOCTITE EDAG 437 E&C	Thermoplastic EMI shielding coating	Burnish resistant Excellent environmental resistance Stable electrical properties after heat cycling Excellent shielding against radiated electromagnetic interference (EMI) and protection against electrostatic discharge (ESD) Room temperature cure	50 – 70 dB at 50 μm	< 0.5	Plastic	23	30 min. at 25°C
LOCTITE EDAG 440 AS E&C	Thermoplastic EMI shielding coating	Excellent shielding against radiated electromagnetic interference (EMI) Protection against electrostatic discharge (ESD) Stable in difficult environmental conditions such as high humidity or heat Room temperature or heat cure	50 – 70 dB at 50 μm	< 0.5	Plastic	17	20 min. at 70°C
LOCTITE EDAG 1415M E&C	Thermoplastic EMI shielding coating	Excellent shielding against radiated electromagnetic interference (EMI) Maintains low resistance after exposure to heat, cold, humidity and salt spray Air drying system that requires no primer or top coat Room temperature or heat cure	60 dB at 25 μm	< 0.015	Plastic	9	30 min. at 70°C

ASSEMBLY-LEVEL EMI SHIELDING GASKETING

Product Name	Description	Key Attributes	Attenuation	Shore A Hardness	Volume Resistivity (Ω·cm)	Tensile Lap Show Strength, N/m² (TLSS)	Recommended Cure
LOCTITE SI 5421	Ag-filled, silicone gasketing material	Room temperature cure Low stress High flexibility	• 80 dB at 10 MHz • 110 dB at 100 MHz • 100 dB at 10 GHz	50 – 65	< 1 × 10 ⁻²	0.7	24 hr. at 25°C

PACKAGE-LEVEL EMI SHIELDING COATINGS

Product Name	Description	Key Attributes	Attenuation	Volume Resistivity (Ω·cm)	Surfaces	Coating Thickness (µm)	Recommended Cure
LOCTITE ABLESTIK EMI 8660S	Package-level, conformal EMI shielding coating	Thinly spray-coated material provides uniform coverage on top and sidewalls of package Excellent adhesion to mold compound Excellent EMI shielding performance at > 100 MHz	90 dB at 3 μm	1.5 × 10 ⁻⁵	• Epoxy mold compound • Copper	3 – 5	1 hr. at 175°C in air
LOCTITE ABLESTIK EMI 8880S	Package-level, conformal EMI shielding coating	Thinly spray-coated material provides uniform coverage on top and sidewalls of package Excellent adhesion to mold compound Excellent EMI shielding performance at > 10 MHz	90 dB at 3 μm	7.9 × 10 ⁻⁶	• Epoxy mold compound • Copper	3 – 5	1 hr. at 175°C in air

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